

EAST text search

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L8	224	257/698.ccls.	US-PGPUB	OR	ON	2006/01/05 16:07
L7	34	(underfill or underfilling or molding or encapsulant or encapsulation) near6 (metal or conductive) near2 (sheet or plate or ring) near12 (crack or cracking or break or breakage or rupture or delamination or fault or fissure)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/05 16:07
L6	5582	(underfill or underfilling or molding or encapsulant or encapsulation) near6 (metal or conductive) near2 (sheet or plate or ring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/05 15:51
L5	182	(underfill or underfilling or molding or encapsulant or encapsulation) near8 (crack or cracking or rupture or break or fissure or breaking or breakage) near3 (prevented or prevent\$4 or impeded\$4 or limit\$4 or decrease\$4 or inhibit\$4 or halt or propag\$5 or hinder) near8 (metal or conductive or sheet or plate or ring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/05 15:49
L4	1045	(underfill or underfilling or molding or encapsulant or encapsulation) near8 (crack or cracking or rupture or break or fissure or breaking or breakage) near8 (metal or conductive or sheet or plate or ring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/05 15:32
L1	186	(underfill or underfilling) near8 (crack or cracking or rupture or break or fissure)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/05 15:31
L3	7	("3716764" "4034027" "5612576" "5699027" "6157085" "6271107").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/05 15:26
L2	5	("5279711" "6261883" "6274391" "6281111" "6521530").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/05 15:24
S57	93	(underfill or underfilling) near8 (bga or ball near grid) near8 (pcb or pwb or package or circuit near board or wiring near board or wiring near substrate or interposer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/21 11:42
S54	29	(US-20020100960-\$ or US-20020121689-\$ or US-20020132463-\$ or US-20020176239-\$ or US-20020180027-\$ or US-20030067066-\$ or US-20030122213-\$ or US-20030146510-\$ or US-20050006751-\$ or US-20050017345-\$ or US-20050218516-\$).did. or (US-4937472-\$ or US-5177594-\$ or US-5188280-\$ or US-6108212-\$ or US-6154370-\$ or US-6261883-\$ or US-6274391-\$ or US-6388207-\$ or US-6479949-\$ or US-6521530-\$ or US-6610934-\$ or US-6707145-\$ or US-6740965-\$ or US-6800947-\$ or US-6828669-\$ or US-6861740-\$ or US-6882039-\$ or US-5283717-\$).did.	US-PGPUB; USPAT	OR	ON	2005/12/13 15:16
S53	5	("5279711" "6261883" "6274391" "6281111" "6521530").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/13 14:57
S52	80	(package or housing or pcb or pwb or circuit near board or wiring near board or interposer) near5 (metal or metallic or conductive or conductor) near2 (sheet or plate or layer) near4 (surface or outside or outer or top or upper) and (contact or electrode or pad or terminal) near5 (channel or groove or trench or recess or isolation or isolating or separated or separation or separating) near20 (via or viahole or feedthrough or feedthru or feed near through or feed near thru or through near hole or thru near hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/13 14:43

S51	614	(package or housing or pcb or pwb or circuit near board or wiring near board or interposer) near5 (metal or metallic or conductive or conductor) near2 (sheet or plate or layer) near4 (surface or outside or outer or top or upper) and (contact or electrode or pad or terminal) near5 (channel or groove or trench or recess or isolation or isolating or separated or separation or separating) and (via or viahole or feedthrough or feedthru or feed near through or feed near thru or through near hole or thru near hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/13 14:40
S50	70	(package or housing or pcb or pwb or circuit near board or wiring near board or interposer) near5 (metal or metallic or conductive or conductor) near2 (sheet or plate or layer) near4 (surface or outside or outer or top or upper) and (contact or electrode or pad or terminal) near5 (channel or groove or trench or recess or isolation or isolating or separated or separation or separating) near8 (via or viahole or feedthrough or feedthru or feed near through or feed near thru or through near hole or thru near hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/13 14:39
S49	937	(package or housing or pcb or pwb or circuit near board or wiring near board or interposer) near5 (metal or metallic or conductive or conductor) near2 (sheet or plate or layer) near4 (surface or outside or outer or top or upper) and (contact or electrode or via or pad or terminal) near5 (channel or groove or trench or recess or isolation or isolating or separated or separation or separating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/13 14:37
S47	104	(package or housing or pcb or pwb or circuit near board or wiring near board or interposer) near5 (distributed or decoupling) near2 (capacitor or capacitance) near4 (surface or outside or outer or top or upper)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/13 14:35
S48	44	("5177594").URPN.	USPAT	OR	ON	2005/12/13 10:29
S46	127	(package or housing or pcb or pwb or circuit near board or wiring near board or interposer) near5 (ground or power or bias or biasing) near (plate or plane) near4 (surface or outside or outer or top or upper) near20 (via or viahole or feedthrough or feedthru or through near hole or thruhole or thru near hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/13 09:22
S45	927	(package or housing or pcb or pwb or circuit near board or wiring near board or interposer) near5 (ground or power or bias or biasing) near (plate or plane) near4 (surface or outside or outer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 16:02
S44	2003	(package or housing or pcb or pwb or circuit near board or wiring near board or interposer) near5 (ground or power or bias or biasing) near2 (plate or plane or sheet) near8 (top or upper or surface or outside or outer or upon or above)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 16:00
S43	341	257/786.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 15:59
S42	133	257/779.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 14:47
S41	424	257/778.ccor. and (solder near ball or bga or ball near grid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 14:14
S40	744	257/778.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 14:14

S39	96	257/730.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 14:07
S38	290	257/700.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 13:46
S37	232	257/698.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 13:30
S36	336	257/691.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 13:06

EAST - interference search notes

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L11	2	((package or interposer or packaging) and (plate or sheet or layer or plane) near4 (metal or metallic or conductive) near8 (underfill or underfilling)).clm.	US-PGPUB	OR	ON	2006/01/05 17:14
L13	3	((package or interposer or packaging) and (etch or etching or etched) near10 (gap or channel or trench) near10 (pad or electrode or terminal or contact)).clm.	US-PGPUB	OR	ON	2006/01/05 17:17
L14	0	((signal or voltage or ground or power) near3 (plane or plate) near8 (underfill or underfilling or underfilled)).clm.	US-PGPUB	OR	ON	2006/01/05 17:18
L15	55	((underfill\$4 or molding or encapsulant or encapsulation) near4 (crack or cracking or fissure or break or breakage or split or splitting or breaking)).clm.	US-PGPUB	OR	ON	2006/01/05 17:21
L16	4	((underfill\$4 or molding or encapsulant or encapsulation) near4 (crack or cracking or fissure or break or breakage or split or splitting or breaking) near10 (conductor or metal or metallic or plate or rigid or rigidity)).clm.	US-PGPUB	OR	ON	2006/01/05 17:22